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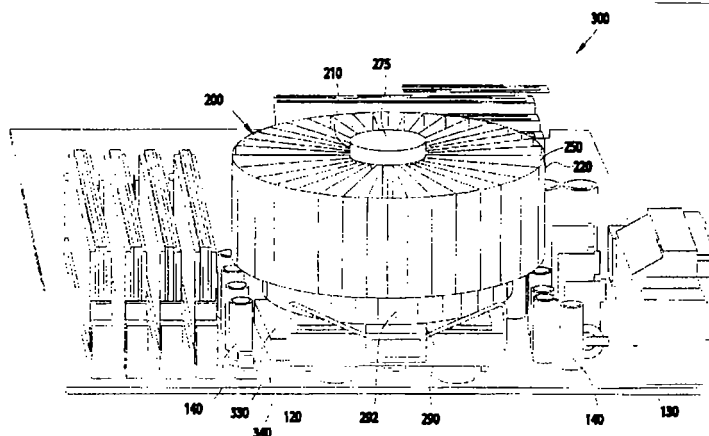
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(54) Title: A HIGH-PERFORMANCE FIN CONFIGURATION FOR AIR-COOLED HEAT DISSIPATION DEVICE



ACTION

(57) Abstract: An enhanced heat dissipation system and a method to extract heat from an integrated circuit device includes a thermally conductive core having upper and lower outer surface areas. The system further includes a first conductive ring having a first array of radially extending fins. The first conductive ring is thermally coupled to the upper surface area. The thermally conductive core includes the first array and the lower outer surface area are of sufficient size to allow components on a motherboard to encroach on to the integrated circuit device when the heat dissipation device is mounted on to the integrated circuit device.

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